



SPECIFICATION

- Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor
- Samsung P/N : CL31C6R8CBCNNNC
- Description : CAP, 6.8pF, 50V, ±0.25pF, C0G, 1206

A. Samsung Part Number

			<u>CL</u>	<u>31</u>	<u>C</u>	<u>6R8</u>	<u>C</u>	<u>B</u>	<u>C</u>	<u>N</u>	<u>N</u>	<u>N</u>	<u>c</u>				
			1	2	3	4	(5)	6	1	8	9	10	1				
1	Series	Samsung	g Multi-la	ayer C	eram	ic Cap	acito	or									
2	Size	1206	(inch co	ode)		L:	3.2	± 0.1	5	mm		W:	1.6	± 0.15	5 mm		
3	Dielectric	C0G					8	Inne	r ele	ctroc	le		Ni				
4	Capacitance	6.8	рF					Tern	ninat	tion			Cu				
5	Capacitance	±0.25	рF					Plati	ing				Sn 10	0%	(Pb	Free)	
	tolerance						9	Proc	luct				Norm	al			
6	Rated Voltage	50	V				10	Spe	cial				Rese	rved for	futur	e use	
\bigcirc	Thickness	0.85	± 0.15	mm			1	Pacl	kagir	ng			Card	board T	ype, 7	7" reel	

B. Samsung Reliablility Test and Judgement condition

	Performance	Test condition						
Capacitance	Within specified tolerance	1Mb±10% 0.5~5Vrms						
Q	536 min							
Insulation	10,000Mohm or 500Mohm µF	Rated Voltage 60~120 sec.						
Resistance	Whichever is Smaller							
Appearance	No abnormal exterior appearance	Microscope (×10)						
Withstanding	No dielectric breakdown or	300% of the rated voltage						
Voltage	mechanical breakdown							
Temperature	C0G							
Characterisitcs	(From -55 $^\circ$ to 125 $^\circ$, Capacitance change shoud be within ±30PPM/ $^\circ$)							
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.						
of Termination	terminal electrode							
Bending Strength	Capacitance change :	Bending to the limit (1mm)						
	within $\pm 5\%$ or ± 0.5 pF whichever is larger	with 1.0mm/sec.						
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder						
	is to be soldered newly	245±5℃, 3±0.3sec.						
		(preheating : 80~120℃ for 10~30sec.)						
Resistance to	Capacitance change :	Solder pot : 270±5℃, 10±1sec.						
Soldering heat	within $\pm 2.5\%$ or ± 0.25 pF whichever is larger							
	Tan δ, IR : initial spec.							

	Performance	Test condition					
Vibration Test	Capacitance change :	Amplitude : 1.5mm					
	within $\pm 2.5\%$ or ± 0.25 pF whichever is larger	From 10Hz to 55Hz (return : 1min.)					
	Tan δ, IR : initial spec.	2hours \times 3 direction (x, y, z)					
Moisture	Capacitance change :	With rated voltage					
Resistance	within $\pm 7.5\%$ or ± 0.75 pF whichever is larger	40±2℃, 90~95%RH, 500+12/-0hrs					
	Q : 122.67 min						
	IR : 500Mohm or 25Mohm · μF						
	Whichever is Smaller						
High Temperature	Capacitance change :	With 200% of the rated voltage					
Resistance	within $\pm 3\%$ or ± 0.3 pF whichever is larger	Max. operating temperature					
	Q : 268 min	1000+48/-0hrs					
	IR : 1000Mohm or 50Mohm · μF						
	Whichever is Smaller						
Temperature	Capacitance change :	1 cycle condition					
Cycling	within $\pm 2.5\%$ or ± 0.25 pF whichever is larger	Min. operating temperature \rightarrow 25 °C					
	Tan δ, IR : initial spec.	\rightarrow Max. operating temperature \rightarrow 25 °C					
		5 cycle test					

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5 °C, 10sec. Max)

* For the more detail Specification, Please refer to the Samsung MLCC catalogue.